Radiation-Hard ASICs for Optical Data Transmission in the ATLAS Pixel Detector

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Outline

Introduction

• Results on IBM 0.25 µm Chips

• Results on Proton Irradiations

• Summary

ATLAS Pixel Detector

- Inner most tracking detector
- Pixel size: 50 μm x 400 μm
- 100 million channels
- Barrel layers at r = 5.1, 12.3 cm
- Disks at z = 50, 65 cm
- Dosage after 10 years:
 - optical link: 30 Mrad or 6 x 10¹⁴ 1-MeV n_{eq}/cm^2





- **VCSEL: Vertical Cavity Surface Emitting Laser diode**
- **VDC: VCSEL Driver Circuit**
- PIN: PiN diode
- **DORIC: Digital Optical Receiver Integrated Circuit**

VDC: VCSEL Driver Circuit

- Convert LVDS input signal into single-ended signal appropriate to drive VCSEL diode
- Output (bright) current: 0 to 20 mA
 - controlled by external current I_{set}
- Standing (dim) current: ~ 1 mA
 improve switching speed
- Duty cycle: $(50 \pm 4)\%$



- Rise & fall times: 1 ns nominal for 80 MHz signals
- "On" voltage of VCSEL: up to 2.3 V at 20 mA for 2.5 V supply
- Constant current consumption!
- use Truelight high-power oxide common cathode VCSEL array K.K. Gan Como03

DORIC: Digital Optical Receiver IC

- Decode Bi-Phase Mark encoded (BPM) clock and command signals from PIN diode
- Input signal: 40-600 μA
- Extract: 40 MHz clock
- Duty cycle: $(50 \pm 4)\%$
- Total timing error: < 1 ns
- Bit Error Rate (BER):
 < 10⁻¹¹ at end of life
- use Truelight common cathode PIN array





Status of VDC & DORIC

- Original design for ATLAS SemiConductor Tracker (SCT)
 AMS 0.8 µm BiPolar in radiation tolerant process (4 V)
- DMILL #1-3: Summer 1999 May 2001
 - □ 0.8 µm CMOS rad-hard process (3.2 V)
 - □ VDC & DORIC #3: meet specs
 - severe degradation of circuit performance in April 2001 proton irradiation
- IBM #1-5: Summer 2001 Dec 2002
 - \Box 0.25 µm CMOS rad-hard process (2.5 V)
 - enclosed layout transistors and guard rings for improved radiation hardness
- IBM 5e: April 2003 engineering run
 - convert 3-layer to 5-layer layout for submission with pixel Module Control Chip (MCC)
 - this is the production run since chips meet specs and sufficient quantity of chips were produced

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VDC-I5e: Bright and Dim Currents vs. I_{set}



- dim current is ~ 1 mA as expected
- bright current measured with 1 Ω in series
- maximum bright current is ~ 13 mA
 - oxide VCSEL has larger effective resistance than p⁺ implanted VCSEL
 - target is 20 mA for efficient annealing from irradiation damage
 - will find out shortly if this is adequate

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VDC-I5e: Rise/Fall Time + Duty Cycle





- specs:
 - \times rise time < 1 ns
 - measured with 44-pin package
 - ♦ acheive faster rise time on opto-board
 - ✓ fall time < 1 ns
 - ✓ duty cycle < $(50 \pm 4)\%$

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DORIC:PIN Current Thresholds with No Bit Errors



• thresholds measured with VDC/DORIC-I5e on BeO opto-board

- thresholds are independent of activity in adjacent channels
- channels with high threshold can be reduced with 2 pF at noise-canceling input channel of PIN

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PIN Current Thresholds vs Compensating Capacitance



- channels with high threshold can be reduced with 2 pF at noise-canceling input channel of PIN
- ⇒ prove the idea of noise cancellation

Status of BeO Opto-board

- converts: optical signal \leftrightarrow electrical signal
- contains 6-7 optical links
- use BeO for heat management but prototype initially in FR-4 for fast turnaround and cost saving
- 1st BeO prototype:
 - many open vias due to insufficient gold filling
 - ✓ opto-links works after via repairs!
- 2nd BeO prototype:
 - recycled BeO boards
 - many shorts due to over filling
 - ➡ use more experienced/expensive vendor

BeO Opto-board



housing



opto-pack



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DORIC

Proton Irradiation at CERN

- use 24 GeV protons at T7 to verify radiation hardness of opto-links
- monitor performance of opto-links in real time
- cold box: irradiate 4 VDC-I5e and 4 DORIC-I5e with no optical components
- shuttle: irradiate 4 opto-boards
 - opto-boards can be moved in and out of beam remotely for VCSEL annealing



Shuttle Test System





• PIN current thresholds for no bit errors remain constant

Proton Induced Bit Errors in PIN



- observed bit errors has been converted to above bit error rate at optical link location
- bit error rate decreases with increasing PIN current as expected
- bit error rate ~ 3 x 10⁻¹⁰ at 100 μ A (1.4 errors/minute)
 - **DORIC** spec: 10^{-11}

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Optical Power vs Dosage



- irradiation procedure: ~ 5 Mrad/day (6 hours) with the rest of day annealing
- optical power decreases with dosage as expected
- annealing at ~ 13 mA recovers some lost power
 - ⇒ need more annealing to see if VCSEL can recover > 70% of power

Summary

- VDC-I5e & DORIC-I5e (IBM 0.25 μm):
 - ✓ radiation hard to > 50 Mrad
 - ✓ meet ATLAS pixel specs
 - ✓ production is completed
- BeO opto-board:
 - ✓ prototype run has verified design
 - will be produced by a second vendor with more experience
- VCSEL lost significant fraction of optical power after irradiation
 await annealing study to see if they can recover > 70% of power
- start opto-link production in Dec 2003